

FEATURES AND SPECIFICATIONS



**1.00mm (.039") Pitch
ExpressModule* (SIOM)**

**78033
Vertical
Through Hole**

Molex's ExpressModule connector offers an improved modular form factor designed for non-stop server and workstation platforms.*

Molex's ExpressModule Connector utilizes the same technology and interface as the PCI Express Connector, with the exception of it being modified to an external I/O modules for non-stop server applications. The connector modification includes a wider lead-in design for blind mating, as well as the addition of the hot plugging capability to facilitate module insertion and removal without system shutdown.*

PCI Express signaling technology incorporates a point to point signaling using differential pairs operating at 2.5Gbps. PCI Express provides adequate bandwidth to support developing I/O such as InfiniBand and 10G fiber channel.

All Molex (PCI) ExpressModule connectors are compliant with PCI-SIG specifications.*

**PCI Express, ExpressModule, and PCI-SIG are trademarks of PIC-SIG*



Features and Benefits

- High-temperature thermoplastic housing for lead-free processing
- Complies with PCI-SIG industry specifications ensure connectors support all ExpressModules available in the market
- Keying design ensures correct mating orientation of card module to edge card connector
- Press fit termination allows solderless termination on high layer count PCBs
- Wider lead-in design to better facilitate blind mating

SPECIFICATIONS

Reference Information

Packaging: Tray
UL File No.: Pending
CSA File No.: Pending
Mates With: 1.57mm (.061") thick ExpressModule
Designed In: Metric

Electrical

Voltage: 50 Volts AC (RMS)/DC
Current: 1.1 A
Contact Resistance: 30 milliohms max
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 1000 Megohms min

Mechanical

Max Terminal Retention Force: 2.94 N min/Terminal
Mating Force: 1.15 N max/contact pair
Un-mating Force: 0.15 N min/contact pair
Durability: 50 Cycles

Physical

Housing: High Temperature Nylon, Black, UL 94V-0
Contact: Copper Alloy
Plating:
Contact Area — 0.76 μ m Gold
Solder Tail Area — Tin
Underplating — Nickel
PCB Thickness: See Ordering Tables
Operating Temperature: - 55 °C to +85 °C

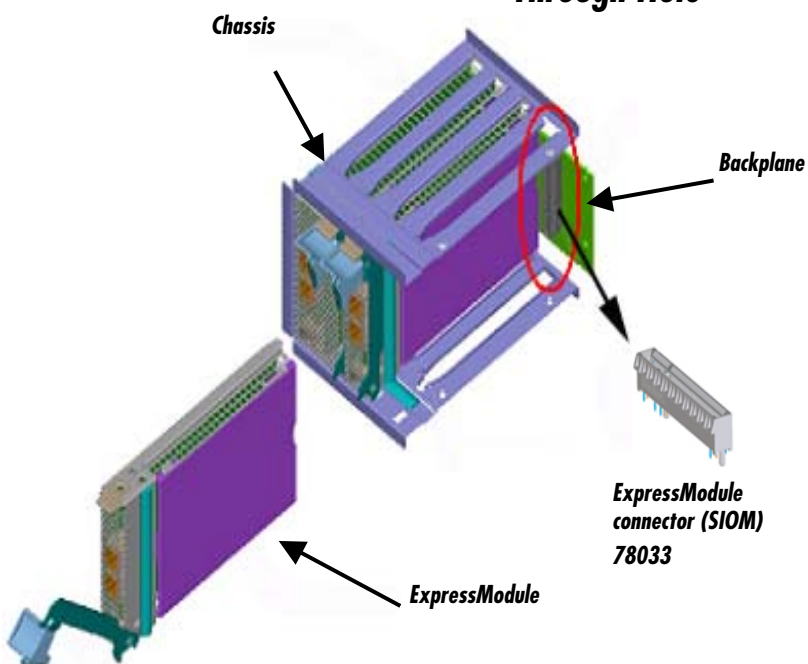
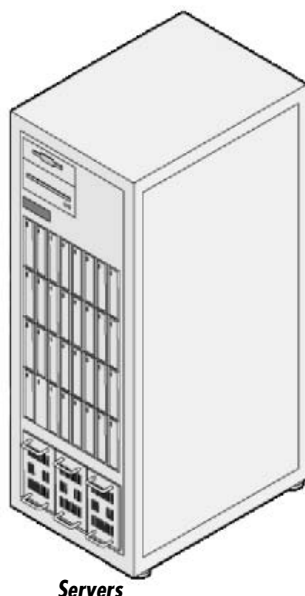
MARKETS AND APPLICATIONS

- Servers
- Storage
- Workstation
- Backplane



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CHASSIS SIDE REMOVED FOR VISIBILITY

ORDERING INFORMATION

Descriptions	Lead-Free Order Number	PC Tail Plating	Plating Thickness	PC Tail Length (mm)	Recommended PCB Thickness
1.00mm (.039") Pitch, ExpressModule (SIOM) Press-fit, 8 Ports, 98 Circuits	78033-0008	Tin	0.76µm (30µ") Gold (Au)	2.54mm (.100")	2.3mm (.09")
	78033-0018			2.79mm (.109")	2.6mm (.102")
	78033-0128			3.43mm(.135")	3.2mm (.125")



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